

LM48823

*LM48823 Mono, Bridge-Tied Load, Ceramic Speaker Driver with I2C
VolumeControl and Reset*



Literature Number: SNAS464E

www.BDTIC.com/TI

Mono, Bridge-Tied Load, Ceramic Speaker Driver with I²C Volume Control and Reset

General Description

The LM48823 is a single supply, mono, ceramic speaker driver with an integrated charge-pump, designed for portable devices, such as cell phones, where board space is at a premium. The LM48823 charge pump allows the device to deliver 5.4V_{RMS} from a single 4.2V supply.

The LM48823 features high power supply rejection ratio (PSRR), 93dB at 217Hz, allowing the device to operate in noisy environments without additional power supply conditioning. Flexible power supply requirements allow operation from 2.0V to 4.5V. The LM48823 features an active low reset input that reverts the device to its default state. Additionally, the LM48823 features a 32-step I²C volume control. The low power Shutdown mode reduces supply current consumption to 0.01μA.

The LM48823's superior click and pop suppression eliminates audible transients on power-up/down and during shutdown. The LM48823 is available in an ultra-small 16-bump micro SMD package (2mmx2mm).

Key Specifications

■ Output Voltage at V _{DD} = 4.2V, R _L = 2.2μF + 15Ω THD+N ≤ 1%	5.4V _{RMS} (typ)
■ Quiescent Power Supply Current at 4.2V	3.3mA (typ)
■ PSRR at 217Hz	93dB (typ)
■ Shutdown current	0.01μA (typ)

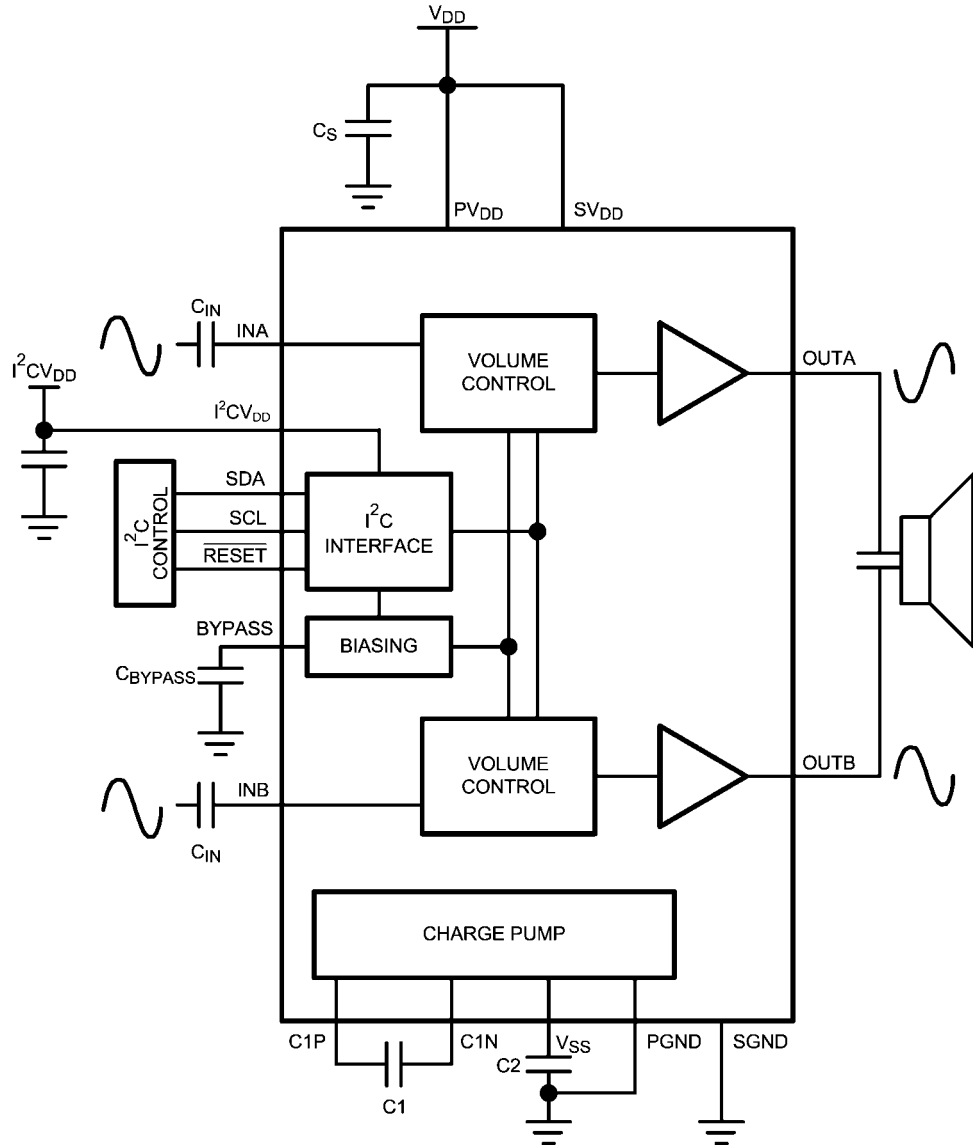
Features

- Integrated Charge Pump
- Bridge-tied Load Output
- High PSRR
- I²C Volume and Mode Control
- Reset Input
- Advanced Click-and-Pop Suppression
- Low Supply Current
- Minimum external components
- Micro-power shutdown
- Available in space-saving 16-bump μSMD package

Applications

- Cell phones
- Smart phones
- Portable media devices
- Notebook PCs

Typical Application

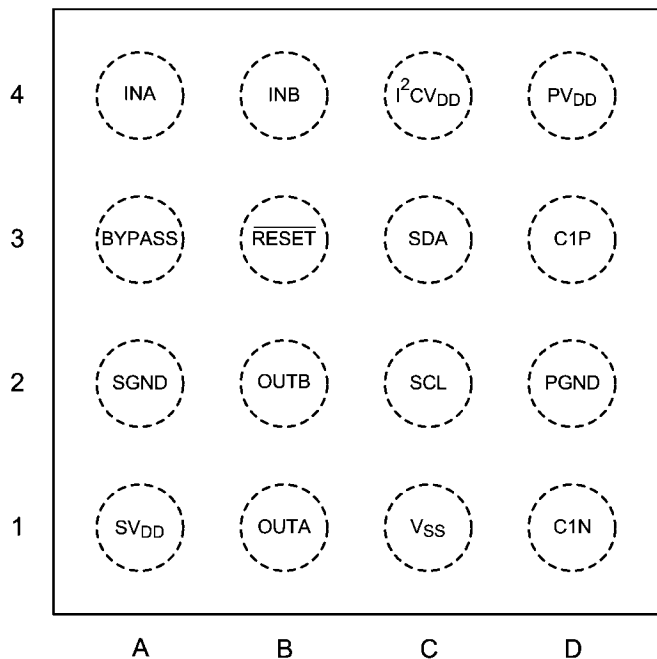


300684e1

FIGURE 1. Typical Audio Amplifier Application Circuit

Connection Diagrams

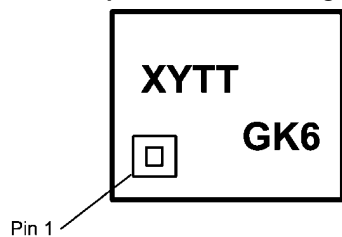
TL Package
2mm x 2mm x 0.8mm



Top View
See NS Package Number TLA1611A

300684e0

16-Bump micro SMD Marking



300684g7

Top View
XY – Date Code
TT – Lot Traceability
G – Boomer Family
K6 – LM48823TL

Ordering Information

Order Number	Package	Package DWG #	Transport Media	MSL Level	Green Status
LM48823TL	16-Bump micro SMD	TLA1611A	250 units on tape and reel	1	NOPB
LM48823TLX	16-Bump micro SMD	TLA1611A	3000 units on tape and reel	1	NOPB

TABLE 1. Bump Descriptions

Pin Designator	Pin Name	Pin Function
A1	SV _{DD}	Signal Power Supply
A2	SGND	Signal Ground
A3	BYPASS	Amplifier Reference Bypass
A4	INA	Amplifier Inverting input A
B1	OUTA	Amplifier Inverting output A
B2	OUTB	Amplifier Non-Inverting Output B
B3	$\overline{\text{RESET}}$	Active Low Reset Input. Connect to V _{DD} for normal operation. Toggle between V _{DD} and GND to reset the device.
B4	INB	Amplifier Non-Inverting Input B
C1	V _{SS}	Charge Pump Output
C2	SCL	I ² C Serial Clock Input
C3	SDA	I ² C Serial Data Input
C4	I ² CV _{DD}	I ² C Supply Voltage
D1	C1N	Charge Pump Flying Capacitor Negative Terminal
D2	PGND	Power Ground
D3	C1P	Charge Pump Flying Capacitor Positive Terminal
D4	PV _{DD}	Power Supply

Absolute Maximum Ratings (Note 1, Note 2)

2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Supply Voltage (Note 1)	5.25V
Storage Temperature	-65°C to +150°C
Input Voltage	-0.3V to $V_{DD} + 0.3V$
Power Dissipation (Note 3)	Internally Limited
ESD Rating (Note 4)	8kV
ESD Rating (Note 5)	250V

Junction Temperature	150°C
Thermal Resistance	
θ_{JA} (typ) - (TLA1611A)	63.2°C/W

Operating Ratings

Temperature Range	
$T_{MIN} \leq T_A \leq T_{MAX}$	$-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$
Supply Voltage	$2.0V \leq V_{DD} \leq 4.5V$
PV_{DD} and SV_{DD}	$1.8V \leq I^2CV_{DD} \leq 4.5V$

Audio Amplifier Electrical Characteristics $V_{DD} = 4.2V$ (Note 1, Note 2)

The following specifications apply for $A_V = 6\text{dB}$, $R_L = 2.2\mu\text{F} + 15\Omega$, $C_1 = C_2 = 2.2\mu\text{F}$, $f = 1\text{kHz}$, unless otherwise specified. Limits apply for $T_A = 25^\circ\text{C}$.

Symbol	Parameter	Conditions	LM48823		Units (Limits)
			Typical (Note 6)	Limits (Note 7)	
I_{DD}	Quiescent Power Supply Current	$V_{IN} = 0V$, $R_L = \infty$	3.3	4.3	mA (max)
I_{SD}	Shutdown Current	Shutdown Enabled	0.01	1	μA (max)
V_{OS}	Differential Output Offset Voltage	$V_{IN} = 0V$	0.5	3	mV (max)
V_{IH}	Logic High Input Threshold	$\overline{\text{RESET}}$		1.4	V (min)
V_{IL}		$\overline{\text{RESET}}$		0.4	V (max)
A_V	Gain	Minimum Gain Setting	-70		dB
		Maximum Gain Setting	24		dB
R_{IN}	Input Resistance	Maximum Gain Setting	9	7 11	k Ω (min) k Ω (max)
		Minimum Gain Setting	80	64 96	k Ω (min) k Ω (max)
V_O	Output Voltage	$R_L = 2.2\mu\text{F} + 15\Omega$, THD+N = 1%	5.4		V_{RMS}
		$f = 1\text{kHz}$ $f = 5\text{kHz}$	3.1		V_{RMS}
THD+N	Total Harmonic Distortion + Noise	$V_O = 4V_{RMS}$	0.015		%
PSRR	Power Supply Rejection Ratio	$V_{RIPPLE} = 200\text{mV}_{P-P}$ Sine, Inputs AC GND, $C_{IN} = 1\mu\text{F}$, input referred			
		$f = 217\text{Hz}$	93	82	dB (min)
		$f = 1\text{kHz}$	93		dB
SNR	Signal-to-Noise-Ratio	$P_{OUT} = 40\text{mW}$, $R_L = 16\Omega$ $f = 1\text{kHz}$	119		dB
ϵ_{OS}	Output Noise	$A_V = 4\text{dB}$, Input Referred, A-weighted Filter	5.5		μV
T_{WU}	Wake-Up Time		200		μs

I2C Interface Characteristics $V_{DD} = 3.0V$ (Note 1, Note 2)

The following specifications apply for $A_V = 6dB$, $R_L = 2.2\mu F + 15\Omega$, $C1 = C2 = 2.2\mu F$, $f = 1kHz$, unless otherwise specified. Limits apply for $T_A = 25^\circ C$.

Symbol	Parameter	Conditions	LM48823		Units (Limits)
			Typical (Note 6)	Limits (Note 7)	
t_1	SCL period			2.5	μs (min)
t_2	SDA Setup Time			100	ns (min)
t_3	SDA Stable Time			0	ns (min)
t_4	Start Condition Time			100	ns (min)
t_5	Stop Condition Time			100	ns (min)
V_{IH}	Logic High Input Threshold			$0.7 \times I^2CV_{DD}$	V (min)
V_{IL}	Logic Low Input Threshold			$0.3 \times I^2CV_{DD}$	V (max)

Note 1: : "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the *Absolute Maximum Ratings* or other conditions beyond those indicated in the *Recommended Operating Conditions* is not implied. The *Recommended Operating Conditions* indicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified.

Note 2: The *Electrical Characteristics* tables list guaranteed specifications under the listed *Recommended Operating Conditions* except as otherwise modified or specified by the *Electrical Characteristics Conditions* and/or Notes. Typical specifications are estimations only and are not guaranteed.

Note 3: The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{JMAX} , θ_{JA} , and the ambient temperature, T_A . The maximum allowable power dissipation is $P_{DMAX} = (T_{JMAX} - T_A) / \theta_{JA}$ or the number given in *Absolute Maximum Ratings*, whichever is lower.

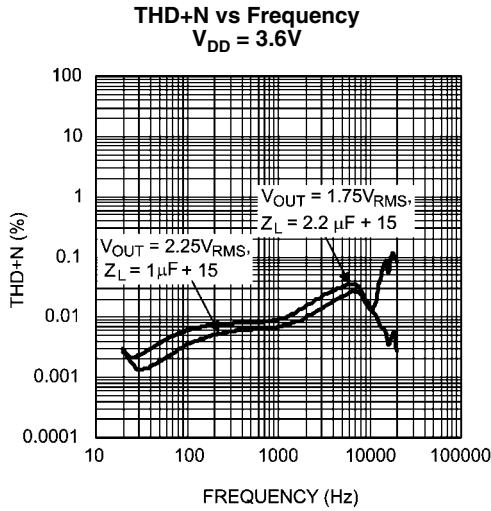
Note 4: Human body model, applicable std. JESD22-A114C.

Note 5: Machine model, applicable std. JESD22-A115-A.

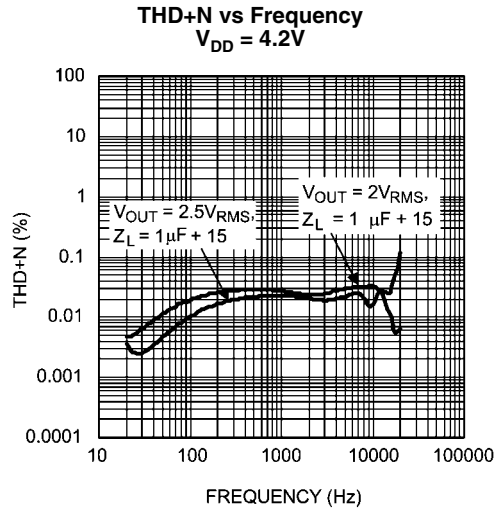
Note 6: Typical values represent most likely parametric norms at $T_A = +25^\circ C$, and at the *Recommended Operation Conditions* at the time of product characterization and are not guaranteed.

Note 7: Datasheet min/max specification limits are guaranteed by test or statistical analysis.

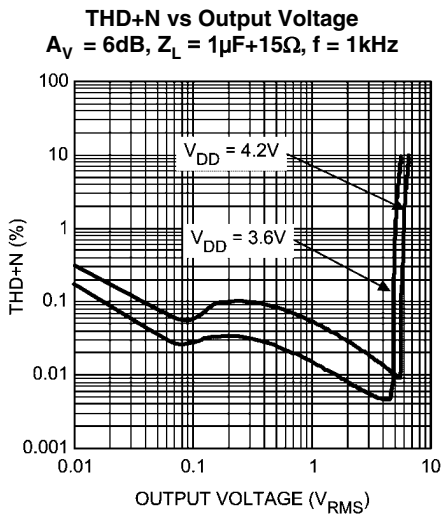
Typical Performance Characteristics



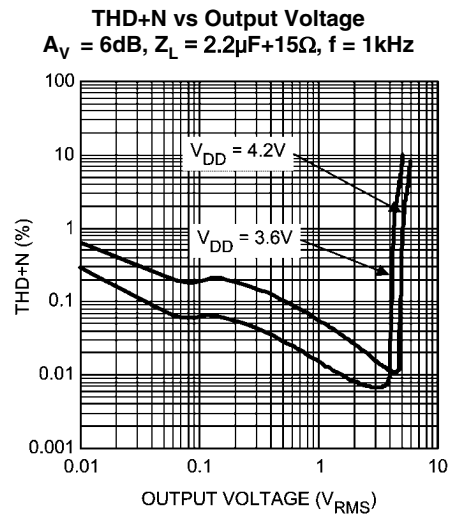
300684g9



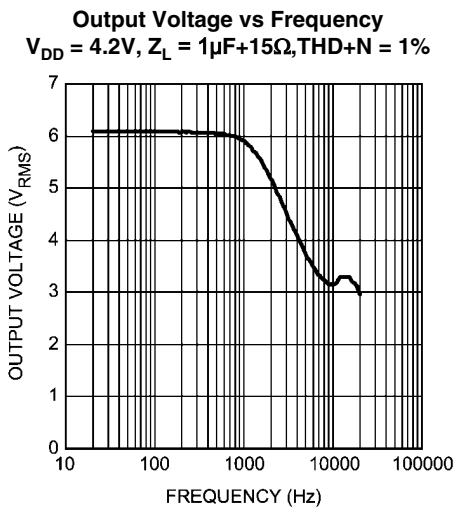
300684h0



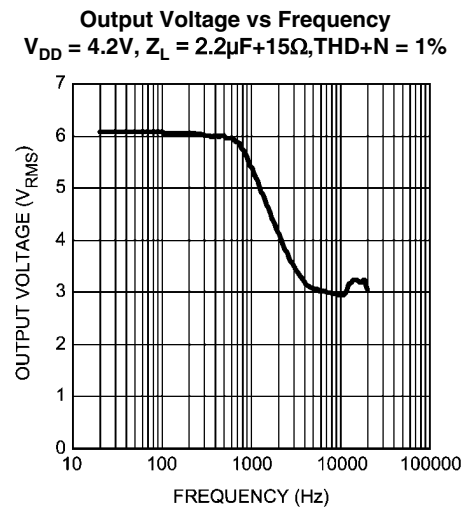
300684i2



300684i3

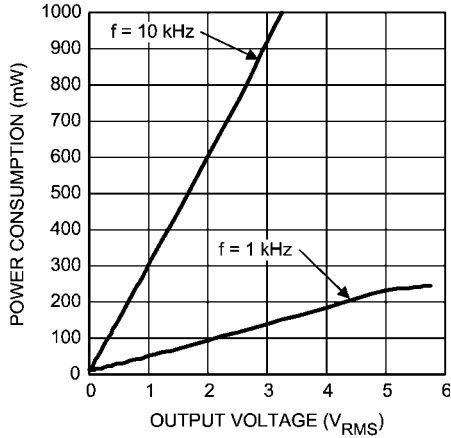


300684i6



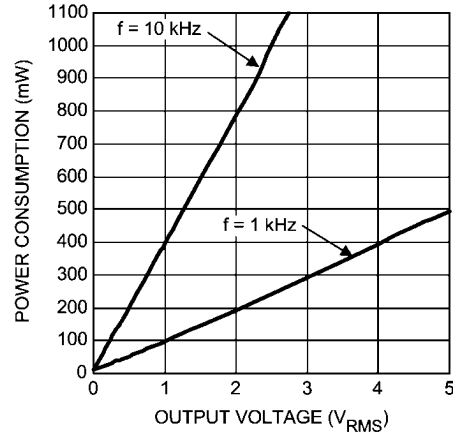
300684i7

Power Consumption vs Output Voltage
 $V_{DD} = 3.6V, Z_L = 1\mu F + 15\Omega$



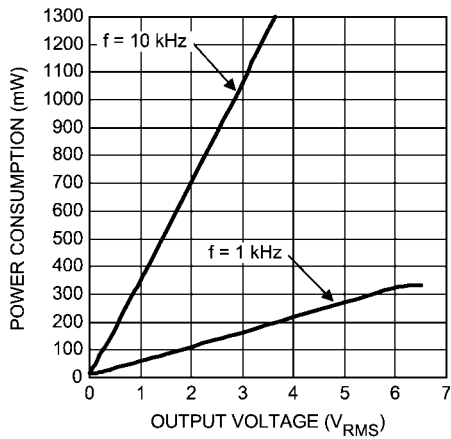
30068418

Power Consumption vs Output Voltage
 $V_{DD} = 3.6V, Z_L = 2.2\mu F + 15\Omega$



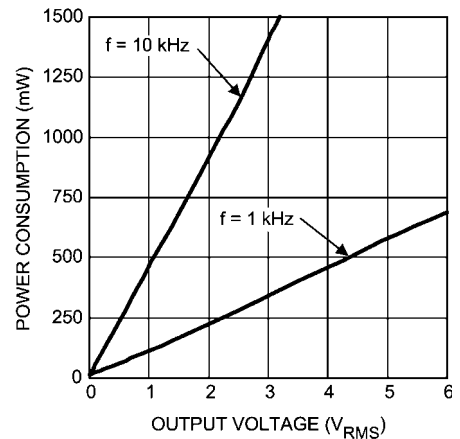
30068419

Power Consumption vs Output Voltage
 $V_{DD} = 4.2V, Z_L = 1\mu F + 15\Omega$



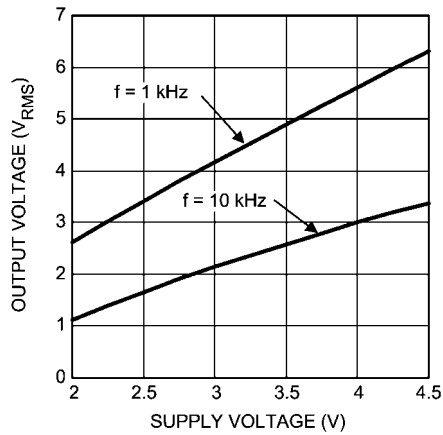
300684g0

Power Consumption vs Output Voltage
 $V_{DD} = 4.2V, Z_L = 2.2\mu F + 15\Omega$



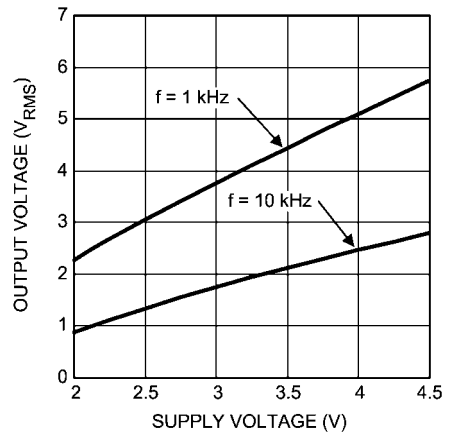
300684g1

Output Voltage vs Supply Voltage
 $Z_L = 1\mu F + 15\Omega, THD+N = 1\%$

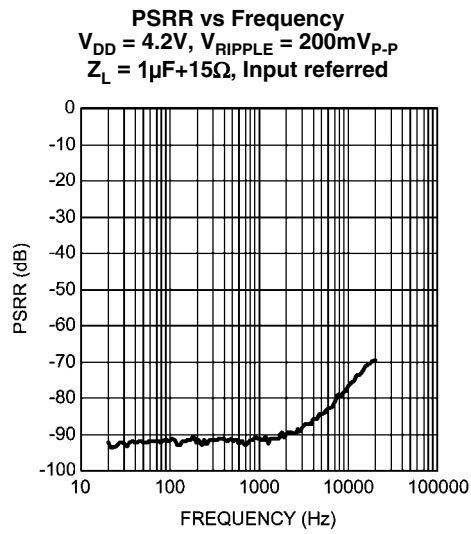


300684g2

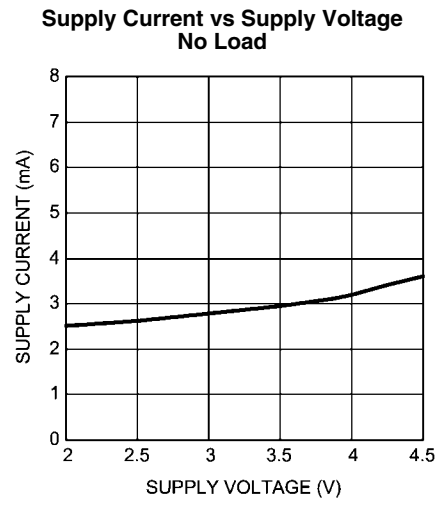
Output Voltage vs Supply Voltage
 $Z_L = 2.2\mu F + 15\Omega, THD+N = 1\%$



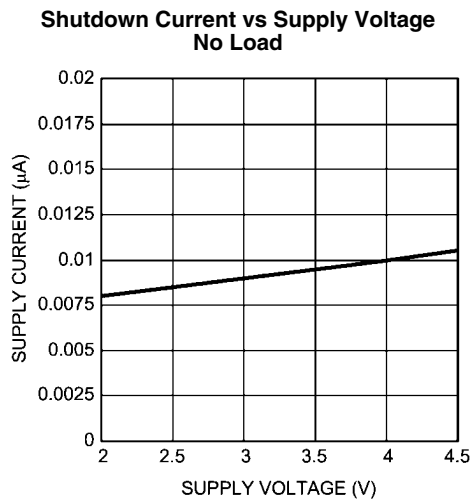
300684g3



300684g4



300684g5



300684g6

Application Information

I²C COMPATIBLE INTERFACE

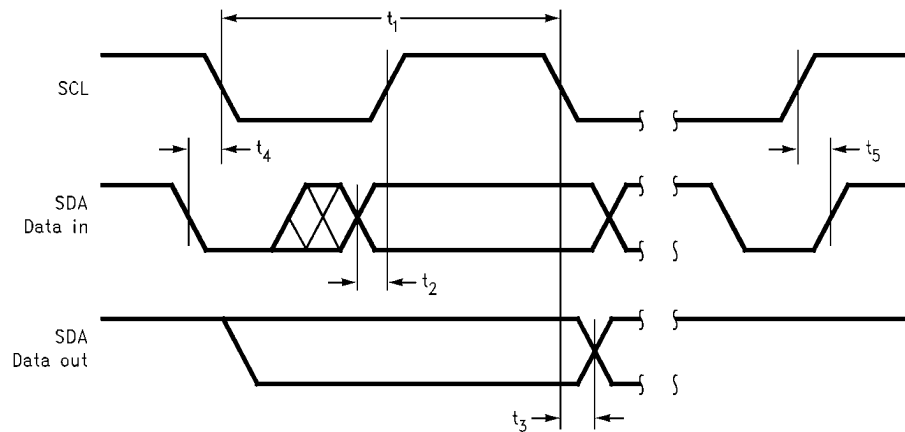
The LM48823 is controlled through an I²C compatible serial interface that consists of a serial data line (SDA) and a serial clock (SCL). The clock line is uni-directional. The data line is bi-directional (open drain). The LM48823 and the master can communicate at clock rates up to 400kHz. Figure 2 shows the I²C interface timing diagram. Data on the SDA line must be stable during the HIGH period of SCL. The LM48823 is a transmit/receive slave-only device, reliant upon the master to generate the SCL signal. Each transmission sequence is framed by a START condition and a STOP condition (Figure 3). Each data word, device address and data, transmitted over the bus is 8 bits long and is always followed by an acknowledge pulse (Figure 4). The LM48823 device address is 1110110.

I²C BUS FORMAT

The I²C bus format is shown in Figure 4. The START signal, the transition of SDA from HIGH to LOW while SCL is HIGH, is generated, alerting all devices on the bus that a device address is being written to the bus.

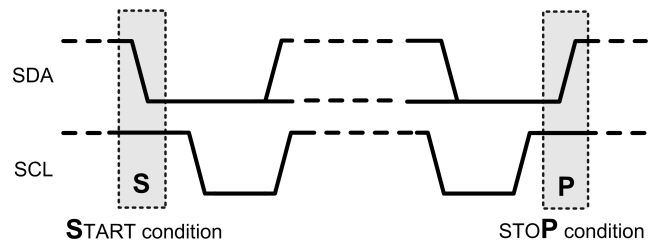
The 7-bit device address is written to the bus, most significant bit (MSB) first, followed by the R/W bit. $R/\overline{W} = 0$ indicates the master is writing to the slave device, $R/\overline{W} = 1$ indicates the master wants to read data from the slave device. Set $R/\overline{W} = 0$; the LM48823 is a WRITE-ONLY device and will not respond to the $R/\overline{W} = 1$. The data is latched in on the rising edge of the clock. Each address bit must be stable while SCL is HIGH. After the last address bit is transmitted, the master device releases SDA, during which time, an acknowledge clock pulse is generated by the slave device. If the LM48823 receives the correct address, the device pulls the SDA line low, generating an acknowledge bit (ACK).

Once the master device registers the ACK bit, the 8-bit register data word is sent. Each data bit should be stable while SCL is HIGH. After the 8-bit register data word is sent, the LM48823 sends another ACK bit. Following the acknowledgement of the register data word, the master issues a STOP bit, allowing SDA to go high while SCL is high.



30068467

FIGURE 2. I²C Timing Diagram



300684g8

FIGURE 3. Start and Stop Diagram

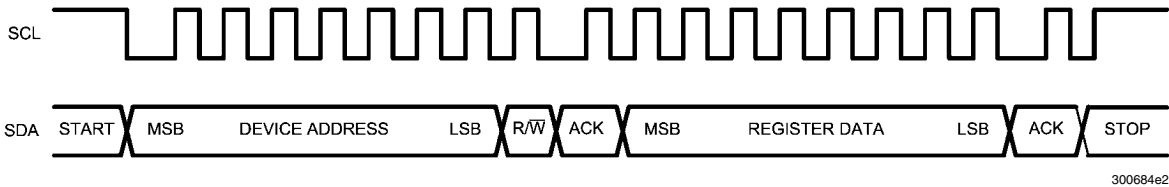


FIGURE 4. Example Write Sequence

TABLE 2. Device Address

	B7	B6	B5	B4	B3	B2	B1	B0 R \bar{W}
Chip Address	1	1	1	0	1	1	0	0

TABLE 3. Mode Control Registers

Register Name	B7	B6	B5	B4	B3	B2	B1	B0
Mode Control	VOL4	VOL3	VOL2	VOL1	VOL0	0	ENABLE_A	ENABLE_B

GENERAL AMPLIFIER FUNCTION

The LM48823 is a ceramic speaker driver that utilizes National’s inverting charge pump technology to deliver over 15V_{P-P} to a 2.2μF ceramic speaker while operating from a single 4.2V supply. The LM48823 features a unique input stage that converts two single-ended audio signals into a mono BTL output. This stereo to mono conversion is useful in applications where a stereo audio source is driving a single ceramic speaker, such as a ringer on a cellular phone. Connect INA and INB as shown in Figure 5 for the stereo-to-mono conversion. When the LM48823 is used with a single-ended mono audio source, connect both INA and INB to the audio source as shown in Figure 6.

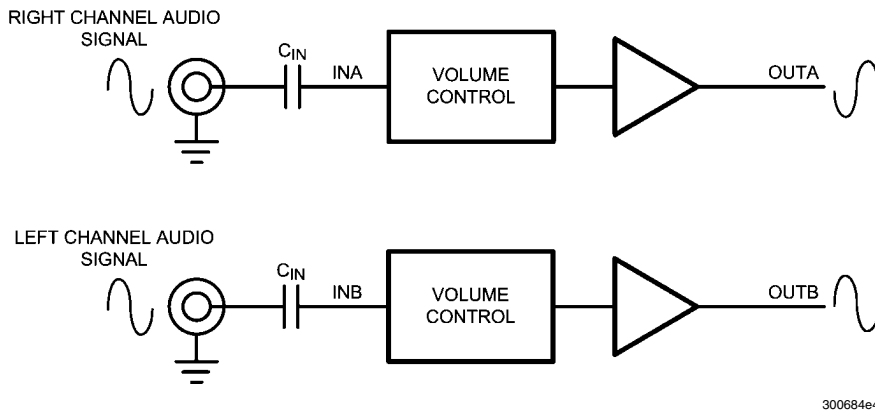


FIGURE 5. Stereo to Mono Conversion Connection Example

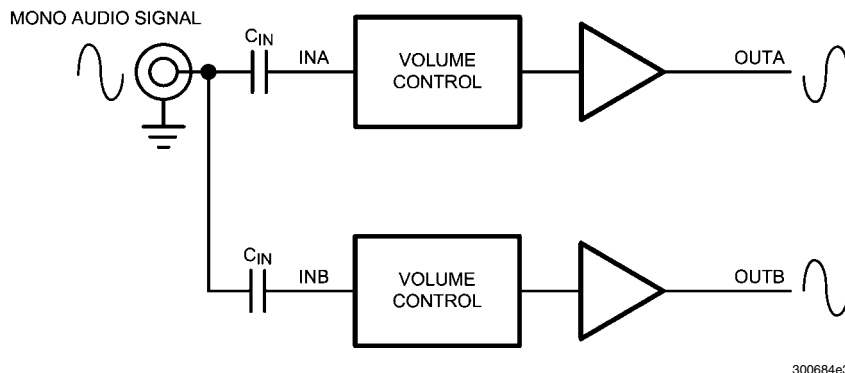


FIGURE 6. Mono Audio Source Connection Example

VOLUME CONTROL

TABLE 4. Volume Control

Volume Step	VOL4	VOL3	VOL2	VOL1	VOL0	Gain (dB)
1	0	0	0	0	0	-70
2	0	0	0	0	1	-56
3	0	0	0	1	0	-46
4	0	0	0	1	1	-38
5	0	0	1	0	0	-32
6	0	0	1	0	1	-28
7	0	0	1	1	0	-24
8	0	0	1	1	1	-21
9	0	1	0	0	0	-18
10	0	1	0	0	1	-15
11	0	1	0	1	0	-12
12	0	1	0	1	1	-10
13	0	1	1	0	0	-8
14	0	1	1	0	1	-6
15	0	1	1	1	0	-4
16	0	1	1	1	1	-2
17	1	0	0	0	0	0
18	1	0	0	0	1	2
19	1	0	0	1	0	4
20	1	0	0	1	1	6
21	1	0	1	0	0	8
22	1	0	1	0	1	10
23	1	0	1	1	0	12
24	1	0	1	1	1	14
25	1	1	0	0	0	16
26	1	1	0	0	1	18
27	1	1	0	1	0	19
28	1	1	0	1	1	20
29	1	1	1	0	0	21
30	1	1	1	0	1	22
31	1	1	1	1	0	23
32	1	1	1	1	1	24

SHUTDOWN FUNCTION

The LM48823 features a low-power shutdown mode that disables the device, lowering the quiescent current to 0.01µA. Set bits B1 (ENABLE_A) and B2 (ENABLE_B) to 0 to disable the amplifiers and charge pump. Set both ENABLE_A and ENABLE_B to 1 for normal operation. Shutdown mode does not clear the I²C register. When re-enabled, the device returns to its previous volume setting. To clear the I²C register, either remove power from the device, or toggle RESET (see RESET section).

RESET

The LM48823 features an active low reset input. Driving RESET low clears the I²C register. Volume control is set to 00000 (-70dB) and both ENABLE_A and ENABLE_B are set to 0, disabling the device. While RESET is low, the LM48823 ignores any I²C data. After the device is reset, and RESET is driven high, the LM48823 remains in shutdown mode with the volume set to -70dB. Re-enable the device by writing to the I²C register.

PROPER SELECTION OF EXTERNAL COMPONENTS

Power Supply Bypassing/Filtering

Proper power supply bypassing is critical for low noise performance and high PSRR. Place the supply bypass capacitors as close to the device as possible. Place a 1µF ceramic capacitor from V_{DD} to GND. Additional bulk capacitance may be added as required.

Bypass Capacitor Selection

The BYPASS capacitor, C_{BYPASS}, improves PSRR, noise rejection and output offset. For best results, use a capacitor of identical value to the input coupling capacitors

Charge Pump Capacitor Selection

Use low ESR ceramic capacitors (less than 100mΩ) for optimum performance.

Charge Pump Flying Capacitor (C1)

The flying capacitor (C1) affects the load regulation and output impedance of the charge pump. A C1 value that is too low

results in a loss of current drive, leading to a loss of amplifier headroom. A higher valued C1 improves load regulation and lowers charge pump output impedance to an extent. Above 2.2µF, the R_{DS(ON)} of the charge pump switches and the ESR of C1 and C2 dominate the output impedance. A lower value capacitor can be used in systems with low maximum output power requirements.

Charge Pump Hold Capacitor (C2)

The value and ESR of the hold capacitor (C2) directly affects the ripple on CPV_{SS}. Increasing the value of C2 reduces output ripple. Decreasing the ESR of C2 reduces both output ripple and charge pump output impedance. A lower value capacitor can be used in systems with low maximum output power requirements.

Input Capacitor Selection

Input capacitors block the DC component of the audio signal, eliminating any conflict between the DC component of the audio source and the bias voltage of the LM48823. The input capacitors create a high-pass filter with the input resistors R_{IN}. The -3dB point of the high pass filter is found using Equation (1) below.

$$f = 1 / 2\pi R_{IN} C_{IN} \quad (\text{Hz}) \quad (1)$$

Where the value of R_{IN} is given in the Electrical Characteristics Table.

High pass filtering the audio signal helps protect the speakers. When the LM48823 is using a single-ended source, power supply noise on the ground is seen as an input signal. Setting the high-pass filter point above the power supply noise frequencies, 217Hz in a GSM phone, for example, filters out the noise such that it is not amplified and heard on the output. Capacitors with a tolerance of 10% or better are recommended for impedance matching and improved CMRR and PSRR.

PCB Layout Guidelines

Minimize trace impedance of the power, ground and all output traces for optimum performance. Voltage loss due to trace resistance between the LM48823 and the load results in decreased output power and efficiency. Trace resistance between the power supply and ground has the same effect as a poorly regulated supply, increased ripple and reduced peak output power. Use wide traces for power supply inputs and amplifier outputs to minimize losses due to trace resistance, as well as route heat away from the device. Proper grounding

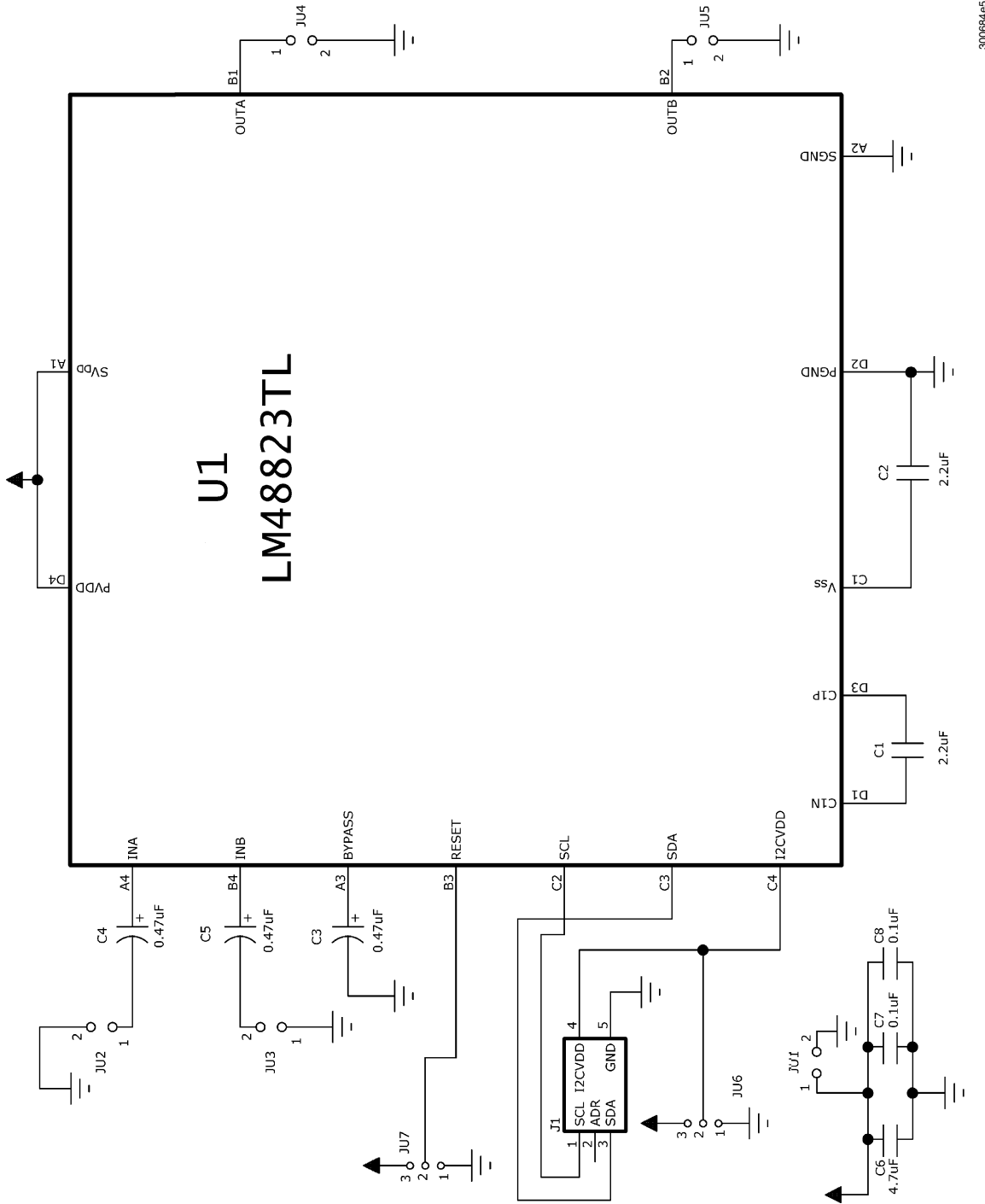
improves audio performance, minimizes crosstalk between channels and prevents switching noise from interfering with the audio signal. Use of power and ground planes is recommended.

Place all digital components and route digital signal traces as far as possible from analog components and traces. Do not run digital and analog traces in parallel on the same PCB layer. If digital and analog signal lines must cross either over or under each other, ensure that they cross in a perpendicular fashion.

LM48823TL Demoboard Bill of Materials

Designator	Quantity	Description
C1, C2	2	2.2 μ F \pm 10% 10V X5R Ceramic Capacitor (603) Panasonic ECJ-1VB1A225K Murata GRM033R6OJ104KE19D
C3 – C5	3	1 μ F \pm 10% 10V Tantalum Capacitor (402) AVX TACK105M010QTA
C6	1	4.7 μ F \pm 10% 6.3V X5R Ceramic Capacitor (603) Panasonic ECJ-1VB0J475K Murata GRM188R6OJ475KE19D
C7, C8	2	0.1 μ F \pm 10% 6.3V X5R Ceramic Capacitor (201) Panasonic ECJ-ZEB0J104K Murata GRM188R61A225KE34D
JU1 – JU5	5	2 Pin Header
JU6, JU7	3	2 Pin Header
J1	1	5-Pin I ² C Header
LM48823TL	1	LM48823TL (16-Bump microSMD)

Demo Board Schematic



300684e5

FIGURE 7. LM48823 Demo Board Schematic

LM48823

PC Board Layout

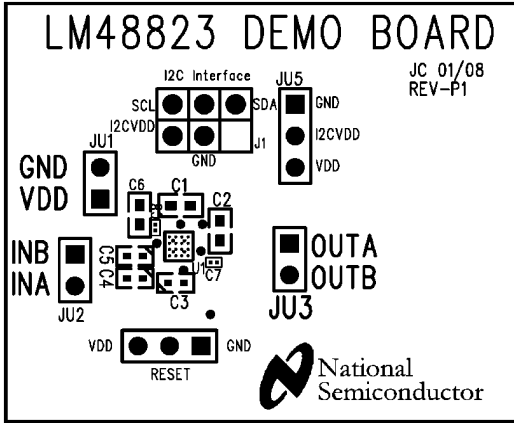


FIGURE 8: Top Silkscreen Layer

300684f0

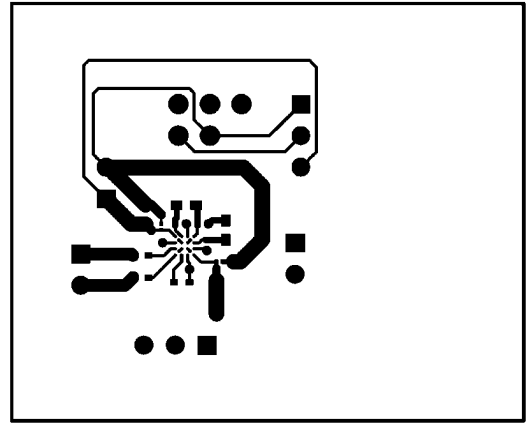


FIGURE 9: Top Layer

300684f1

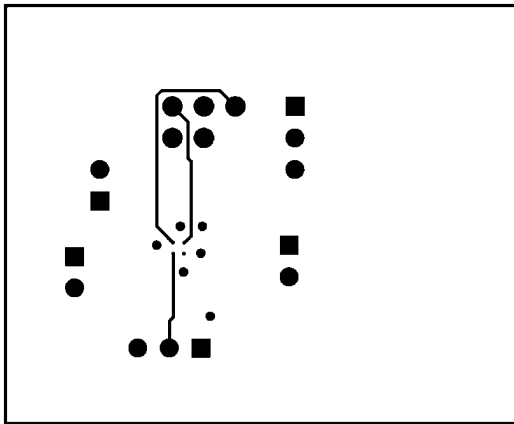


FIGURE 10: Layer 2

300684e7

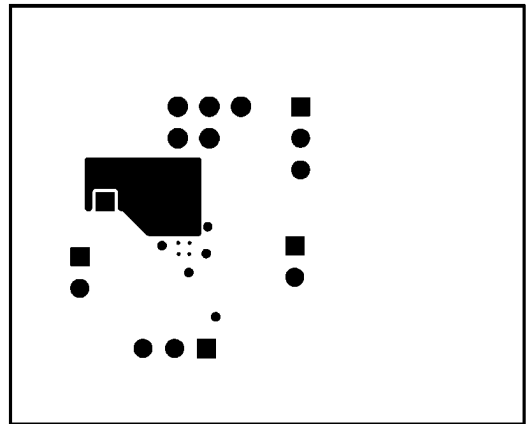


FIGURE 11: Layer 3

300684e8

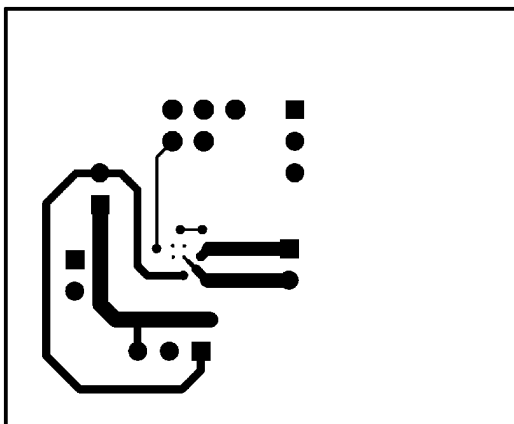


FIGURE 12: Bottom Layer

300684e6

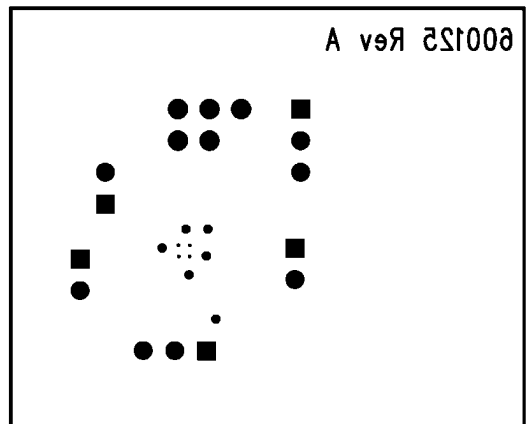


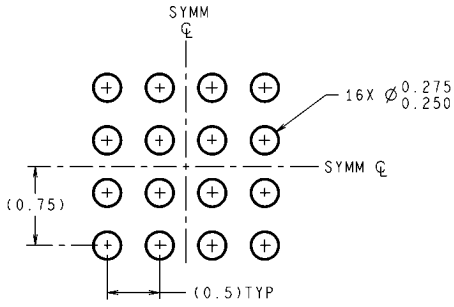
FIGURE 13: Bottom Silkscreen

300684e9

Revision History

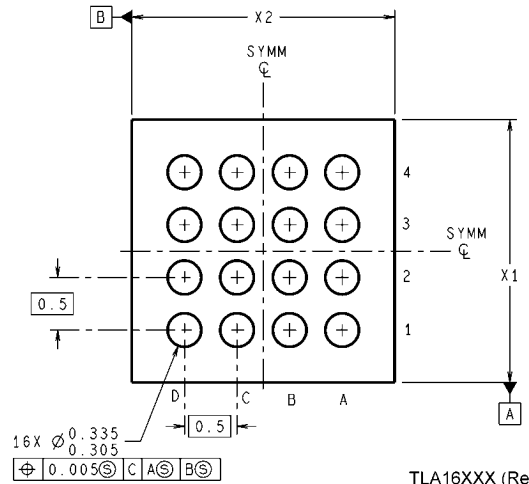
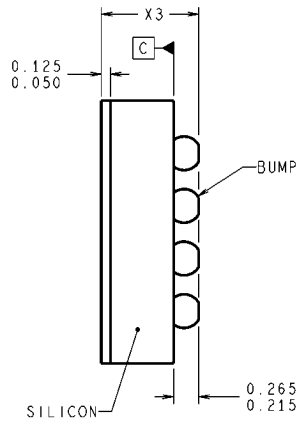
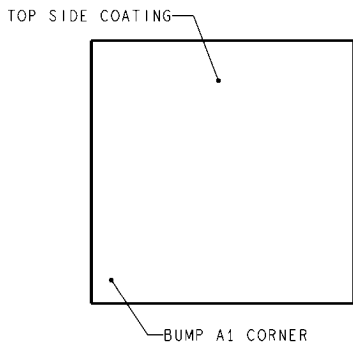
Rev	Date	Description
1.0	06/27/08	Initial release.
1.01	07/15/08	Edited the Ordering Information table.
1.02	10/08/10	Updated some Limits (under Gain) in the Volume Control table.

Physical Dimensions inches (millimeters) unless otherwise noted



DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY

LAND PATTERN RECOMMENDATION



TLA16XXX (Rev C)

16-Bump micro SMD
Order Number LM48823TL
NS Package Number TLA1611A
 $X_1 = 1.970 \pm 0.03$ $X_2 = 1.970 \pm 0.03$ $X_3 = 0.6 \pm 0.075$

Notes

Notes

For more National Semiconductor product information and proven design tools, visit the following Web sites at:
www.national.com

Products		Design Support	
Amplifiers	www.national.com/amplifiers	WEBENCH® Tools	www.national.com/webench
Audio	www.national.com/audio	App Notes	www.national.com/appnotes
Clock and Timing	www.national.com/timing	Reference Designs	www.national.com/refdesigns
Data Converters	www.national.com/adc	Samples	www.national.com/samples
Interface	www.national.com/interface	Eval Boards	www.national.com/evalboards
LVDS	www.national.com/lvds	Packaging	www.national.com/packaging
Power Management	www.national.com/power	Green Compliance	www.national.com/quality/green
Switching Regulators	www.national.com/switchers	Distributors	www.national.com/contacts
LDOs	www.national.com/ldo	Quality and Reliability	www.national.com/quality
LED Lighting	www.national.com/led	Feedback/Support	www.national.com/feedback
Voltage References	www.national.com/vref	Design Made Easy	www.national.com/easy
PowerWise® Solutions	www.national.com/powerwise	Applications & Markets	www.national.com/solutions
Serial Digital Interface (SDI)	www.national.com/sdi	Mil/Aero	www.national.com/milaero
Temperature Sensors	www.national.com/tempensors	SolarMagic™	www.national.com/solarmagic
PLL/VCO	www.national.com/wireless	PowerWise® Design University	www.national.com/training

THE CONTENTS OF THIS DOCUMENT ARE PROVIDED IN CONNECTION WITH NATIONAL SEMICONDUCTOR CORPORATION ("NATIONAL") PRODUCTS. NATIONAL MAKES NO REPRESENTATIONS OR WARRANTIES WITH RESPECT TO THE ACCURACY OR COMPLETENESS OF THE CONTENTS OF THIS PUBLICATION AND RESERVES THE RIGHT TO MAKE CHANGES TO SPECIFICATIONS AND PRODUCT DESCRIPTIONS AT ANY TIME WITHOUT NOTICE. NO LICENSE, WHETHER EXPRESS, IMPLIED, ARISING BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT.

TESTING AND OTHER QUALITY CONTROLS ARE USED TO THE EXTENT NATIONAL DEEMS NECESSARY TO SUPPORT NATIONAL'S PRODUCT WARRANTY. EXCEPT WHERE MANDATED BY GOVERNMENT REQUIREMENTS, TESTING OF ALL PARAMETERS OF EACH PRODUCT IS NOT NECESSARILY PERFORMED. NATIONAL ASSUMES NO LIABILITY FOR APPLICATIONS ASSISTANCE OR BUYER PRODUCT DESIGN. BUYERS ARE RESPONSIBLE FOR THEIR PRODUCTS AND APPLICATIONS USING NATIONAL COMPONENTS. PRIOR TO USING OR DISTRIBUTING ANY PRODUCTS THAT INCLUDE NATIONAL COMPONENTS, BUYERS SHOULD PROVIDE ADEQUATE DESIGN, TESTING AND OPERATING SAFEGUARDS.

EXCEPT AS PROVIDED IN NATIONAL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, NATIONAL ASSUMES NO LIABILITY WHATSOEVER, AND NATIONAL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY RELATING TO THE SALE AND/OR USE OF NATIONAL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS PRIOR WRITTEN APPROVAL OF THE CHIEF EXECUTIVE OFFICER AND GENERAL COUNSEL OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

Life support devices or systems are devices which (a) are intended for surgical implant into the body, or (b) support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in a significant injury to the user. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system or to affect its safety or effectiveness.

National Semiconductor and the National Semiconductor logo are registered trademarks of National Semiconductor Corporation. All other brand or product names may be trademarks or registered trademarks of their respective holders.

Copyright© 2010 National Semiconductor Corporation

For the most current product information visit us at www.national.com



National Semiconductor
Americas Technical
Support Center
Email: support@nsc.com
Tel: 1-800-272-9959

National Semiconductor Europe
Technical Support Center
Email: europe.support@nsc.com

National Semiconductor Asia
Pacific Technical Support Center
Email: ap.support@nsc.com

National Semiconductor Japan
Technical Support Center
Email: jpn.feedback@nsc.com

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated

www.BDTIC.com/TI